



Material Content Data Sheet



Sales Product Name		1ED020I12-B2		Issued		28. August 2013		
MA#		MA001070338						
Package		PG-DSO-16-15		Weight*		449.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.549	1.01	1.01	10127	10127
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		70	
	non noble metal	zinc	7440-66-6	0.126	0.03		281	
	non noble metal	iron	7439-89-6	2.521	0.56		5613	
wire	non noble metal	copper	7440-50-8	102.369	22.79	23.39	227922	233886
	noble metal	gold	7440-57-5	0.646	0.14	0.14	1438	1438
	encapsulation	organic material	carbon black	1333-86-4	1.664	0.37		3706
encapsulation	plastics	epoxy resin	-	44.938	10.01		100054	
	inorganic material	silicondioxide	60676-86-0	286.274	63.73	74.11	637385	741145
leadfinish	non noble metal	tin	7440-31-5	2.873	0.64	0.64	6397	6397
plating	noble metal	silver	7440-22-4	1.017	0.23	0.23	2264	2264
glue	plastics	epoxy resin	-	0.533	0.12		1186	
	noble metal	silver	7440-22-4	1.598	0.36	0.48	3557	4743
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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